

# Thyristor Module

$$V_{RRM} = 2 \times 1200 \text{ V}$$

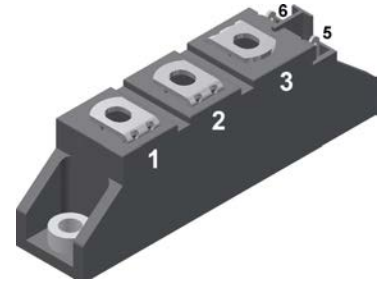
$$I_{TAV} = 85 \text{ A}$$

$$V_T = 1,34 \text{ V}$$


Phase leg

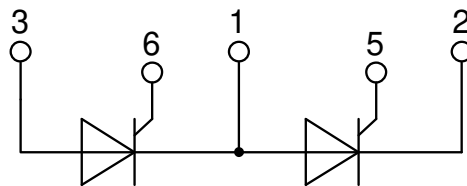
Part number

**MCC72-12io8B**



Backside: isolated

 E72873



### Features / Advantages:

- Thyristor for line frequency
- Planar passivated chip
- Long-term stability
- Direct Copper Bonded Al<sub>2</sub>O<sub>3</sub>-ceramic

### Applications:

- Line rectifying 50/60 Hz
- Softstart AC motor control
- DC Motor control
- Power converter
- AC power control
- Lighting and temperature control

### Package: TO-240AA

- Isolation Voltage: 4800 V~
- Industry standard outline
- RoHS compliant
- Soldering pins for PCB mounting
- Base plate: DCB ceramic
- Reduced weight
- Advanced power cycling

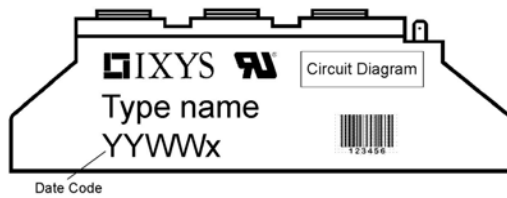
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Thyristor				Ratings			
Symbol	Definition	Conditions	min.	typ.	max.	Unit	
$V_{RSM/DSM}$	max. non-repetitive reverse/forward blocking voltage	$T_{VJ} = 25^{\circ}C$			1300	V	
$V_{RRM/DRM}$	max. repetitive reverse/forward blocking voltage	$T_{VJ} = 25^{\circ}C$			1200	V	
$I_{RD}$	reverse current, drain current	$V_{R/D} = 1200 V$	$T_{VJ} = 25^{\circ}C$		200	$\mu A$	
		$V_{R/D} = 1200 V$	$T_{VJ} = 125^{\circ}C$		5	mA	
$V_T$	forward voltage drop	$I_T = 150 A$	$T_{VJ} = 25^{\circ}C$		1,34	V	
		$I_T = 300 A$			1,74	V	
		$I_T = 150 A$	$T_{VJ} = 125^{\circ}C$		1,34	V	
		$I_T = 300 A$			1,82	V	
$I_{TAV}$	average forward current	$T_C = 85^{\circ}C$	$T_{VJ} = 125^{\circ}C$		85	A	
$I_{T(RMS)}$	RMS forward current	180° sine			133	A	
$V_{T0}$	threshold voltage	} for power loss calculation only	$T_{VJ} = 125^{\circ}C$		0,85	V	
$r_T$	slope resistance				3,2	m $\Omega$	
$R_{thJC}$	thermal resistance junction to case				0,3	K/W	
$R_{thCH}$	thermal resistance case to heatsink			0,2		K/W	
$P_{tot}$	total power dissipation		$T_C = 25^{\circ}C$		333	W	
$I_{TSM}$	max. forward surge current	$t = 10 \text{ ms}; (50 \text{ Hz}), \text{ sine}$	$T_{VJ} = 45^{\circ}C$		1,70	kA	
		$t = 8,3 \text{ ms}; (60 \text{ Hz}), \text{ sine}$	$V_R = 0 V$		1,84	kA	
		$t = 10 \text{ ms}; (50 \text{ Hz}), \text{ sine}$	$T_{VJ} = 125^{\circ}C$		1,45	kA	
		$t = 8,3 \text{ ms}; (60 \text{ Hz}), \text{ sine}$	$V_R = 0 V$		1,56	kA	
$I^2t$	value for fusing	$t = 10 \text{ ms}; (50 \text{ Hz}), \text{ sine}$	$T_{VJ} = 45^{\circ}C$		14,5	kA <sup>2</sup> s	
		$t = 8,3 \text{ ms}; (60 \text{ Hz}), \text{ sine}$	$V_R = 0 V$		14,0	kA <sup>2</sup> s	
		$t = 10 \text{ ms}; (50 \text{ Hz}), \text{ sine}$	$T_{VJ} = 125^{\circ}C$		10,4	kA <sup>2</sup> s	
		$t = 8,3 \text{ ms}; (60 \text{ Hz}), \text{ sine}$	$V_R = 0 V$		10,1	kA <sup>2</sup> s	
$C_J$	junction capacitance	$V_R = 400V \quad f = 1 \text{ MHz}$	$T_{VJ} = 25^{\circ}C$		119	pF	
$P_{GM}$	max. gate power dissipation	$t_p = 30 \mu s$	$T_C = 125^{\circ}C$		10	W	
		$t_p = 300 \mu s$			5	W	
$P_{GAV}$	average gate power dissipation				0,5	W	
$(di/dt)_{cr}$	critical rate of rise of current	$T_{VJ} = 125^{\circ}C; f = 50 \text{ Hz}$ repetitive, $I_T = 250 A$			150	A/ $\mu s$	
		$t_p = 200 \mu s; di_G/dt = 0,45 \text{ A}/\mu s;$ $I_G = 0,45A; V_D = \frac{2}{3} V_{DRM}$ non-repet., $I_T = 85 A$			500	A/ $\mu s$	
$(dv/dt)_{cr}$	critical rate of rise of voltage	$V_D = \frac{2}{3} V_{DRM}$ $R_{GK} = \infty$ ; method 1 (linear voltage rise)	$T_{VJ} = 125^{\circ}C$		1000	V/ $\mu s$	
$V_{GT}$	gate trigger voltage	$V_D = 6 V$	$T_{VJ} = 25^{\circ}C$		2,5	V	
			$T_{VJ} = -40^{\circ}C$		2,6	V	
$I_{GT}$	gate trigger current	$V_D = 6 V$	$T_{VJ} = 25^{\circ}C$		150	mA	
			$T_{VJ} = -40^{\circ}C$		200	mA	
$V_{GD}$	gate non-trigger voltage	$V_D = \frac{2}{3} V_{DRM}$	$T_{VJ} = 125^{\circ}C$		0,2	V	
$I_{GD}$	gate non-trigger current				10	mA	
$I_L$	latching current	$t_p = 10 \mu s$	$T_{VJ} = 25^{\circ}C$		450	mA	
		$I_G = 0,45A; di_G/dt = 0,45 \text{ A}/\mu s$					
$I_H$	holding current	$V_D = 6 V \quad R_{GK} = \infty$	$T_{VJ} = 25^{\circ}C$		200	mA	
$t_{gd}$	gate controlled delay time	$V_D = \frac{1}{2} V_{DRM}$ $I_G = 0,45A; di_G/dt = 0,45 \text{ A}/\mu s$	$T_{VJ} = 25^{\circ}C$		2	$\mu s$	
$t_q$	turn-off time	$V_R = 100 V; I_T = 150A; V_D = \frac{2}{3} V_{DRM}$ $di/dt = 10 \text{ A}/\mu s; dv/dt = 20 \text{ V}/\mu s; t_p = 200 \mu s$	$T_{VJ} = 100^{\circ}C$		185	$\mu s$	



Package TO-240AA				Ratings			
Symbol	Definition	Conditions	min.	typ.	max.	Unit	
$I_{RMS}$	RMS current	per terminal			200	A	
$T_{VJ}$	virtual junction temperature		-40		125	°C	
$T_{op}$	operation temperature		-40		100	°C	
$T_{stg}$	storage temperature		-40		125	°C	
<b>Weight</b>					81	g	
$M_D$	mounting torque		2,5		4	Nm	
$M_T$	terminal torque		2,5		4	Nm	
$d_{Spp/App}$	creepage distance on surface   striking distance through air	terminal to terminal	13,0	9,7		mm	
$d_{Spb/Apb}$		terminal to backside	16,0	16,0		mm	
$V_{ISOL}$	isolation voltage	t = 1 second		4800		V	
		t = 1 minute	50/60 Hz, RMS; $I_{ISOL} \leq 1$ mA	4000		V	



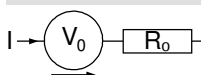
Ordering	Ordering Number	Marking on Product	Delivery Mode	Quantity	Code No.
Standard	MCC72-12io8B	MCC72-12io8B	Box	36	457914

Similar Part	Package	Voltage class
MCMA85P1200TA	TO-240AA-1B	1200
MCMA110P1200TA	TO-240AA-1B	1200

**Equivalent Circuits for Simulation**

\* on die level

$T_{VJ} = 125^\circ\text{C}$

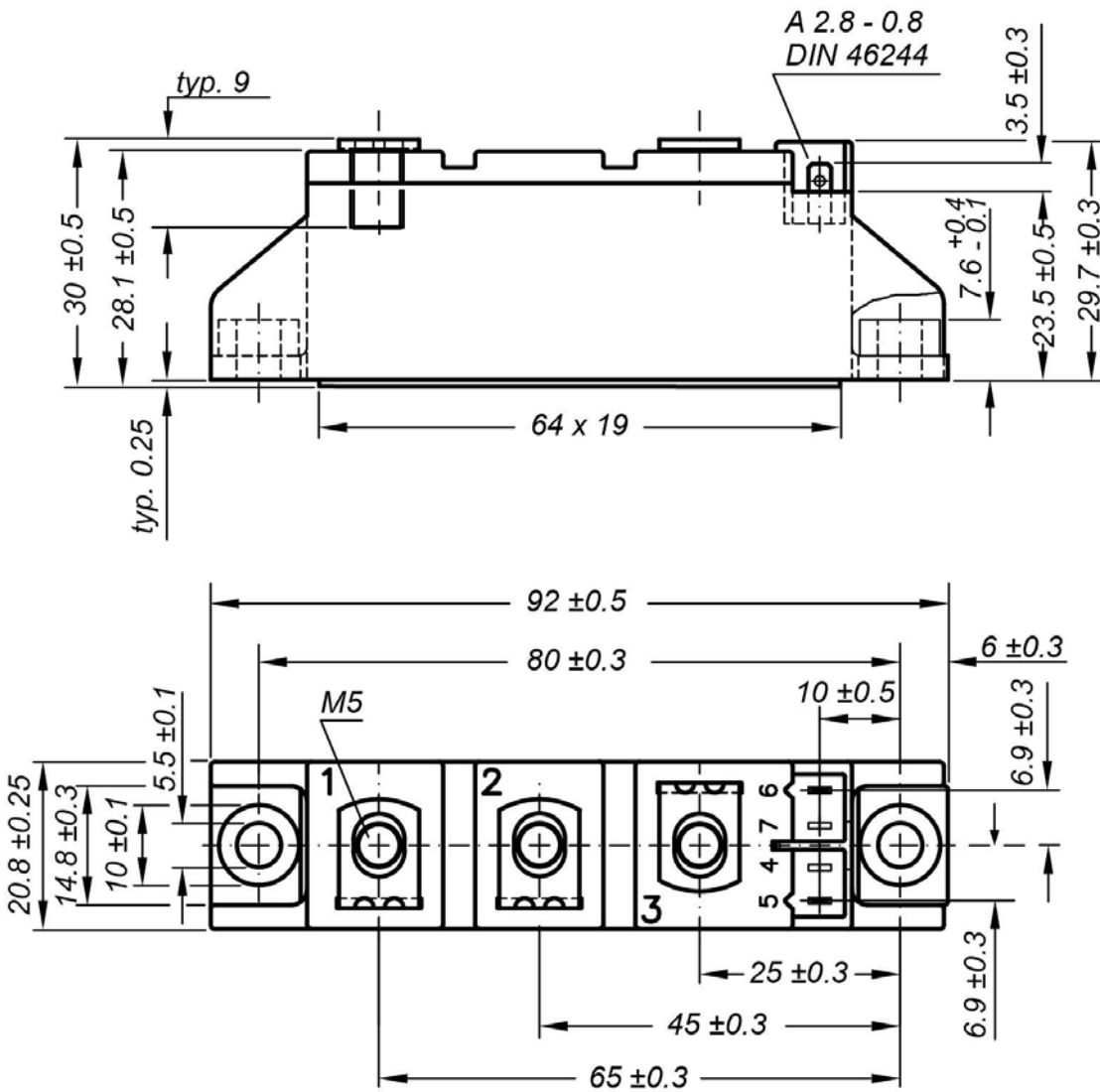


**Thyristor**

$V_{0 \max}$	threshold voltage	0,85	V
$R_{0 \max}$	slope resistance *	2	mΩ



**Outlines TO-240AA**

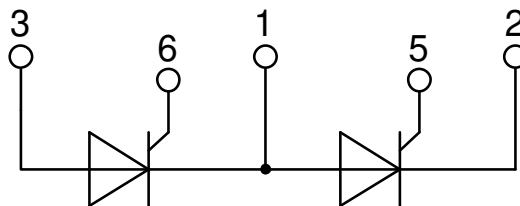


**Optional accessories for modules**

Keyed gate/cathode twin plugs with wire length = 350 mm, gate = white, cathode = red

Type ZY 200L (L = Left for pin pair 4/5)

Type ZY 200R (R = Right for pin pair 6/7) } UL 758, style 3751



**Thyristor**

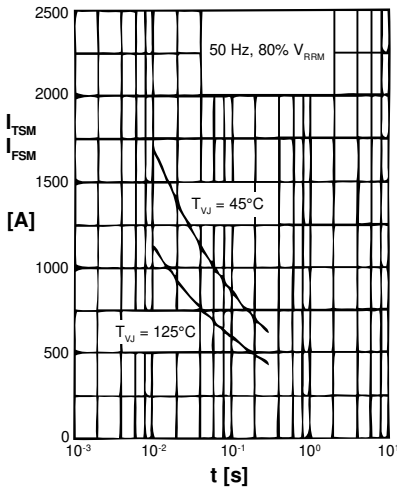


Fig. 1 Surge overload current  
 $I_{TSM}$ ,  $I_{FSM}$ : Crest value,  $t$ : duration

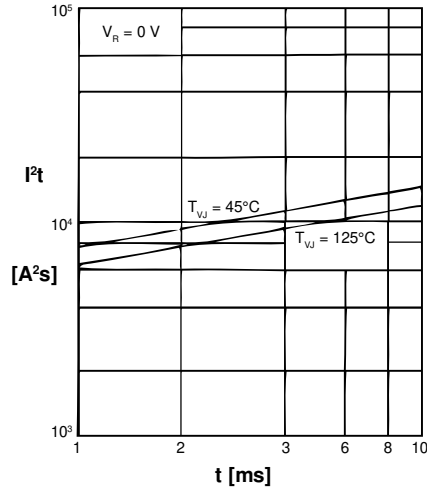


Fig. 2  $I^2t$  versus time (1-10 ms)

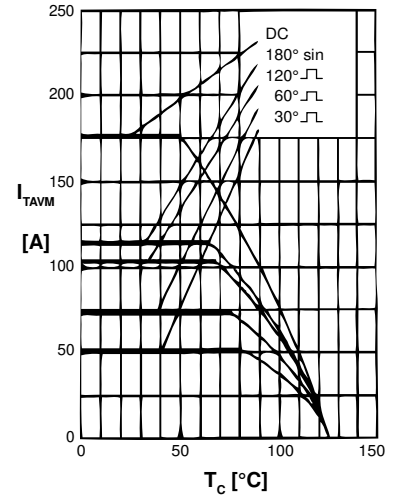


Fig. 3 Maximum forward current at case temperature

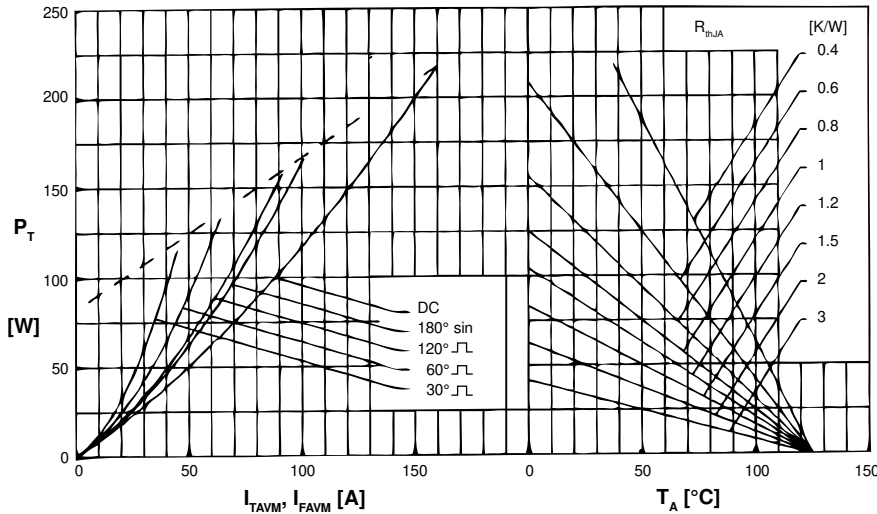


Fig. 4 Power dissipation vs. onstate current and ambient temperature (per thyristor/diode)

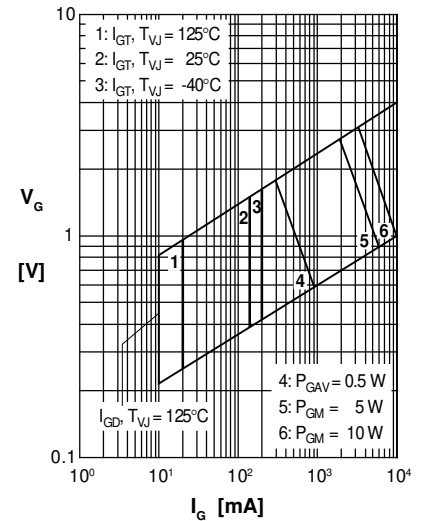


Fig. 5 Gate trigger characteristics

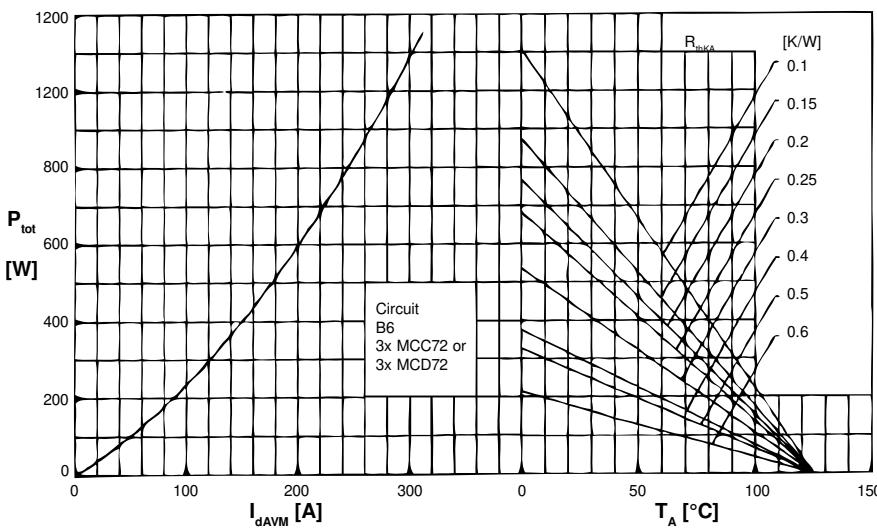


Fig. 6 Three phase rectifier bridge: Power dissipation versus direct output current and ambient temperature

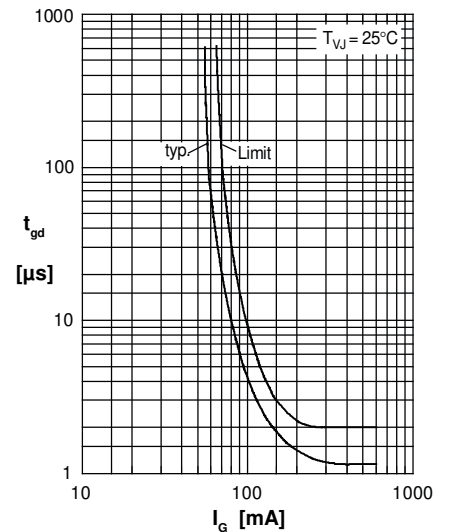


Fig. 7 Gate trigger delay time

**Thyristor**

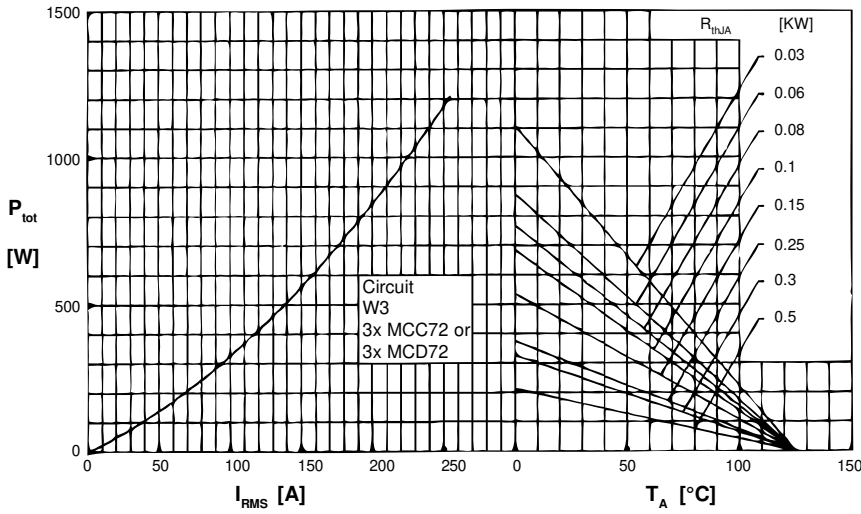


Fig. 8 Three phase AC-controller: Power dissipation versus RMS output current and ambient temperature

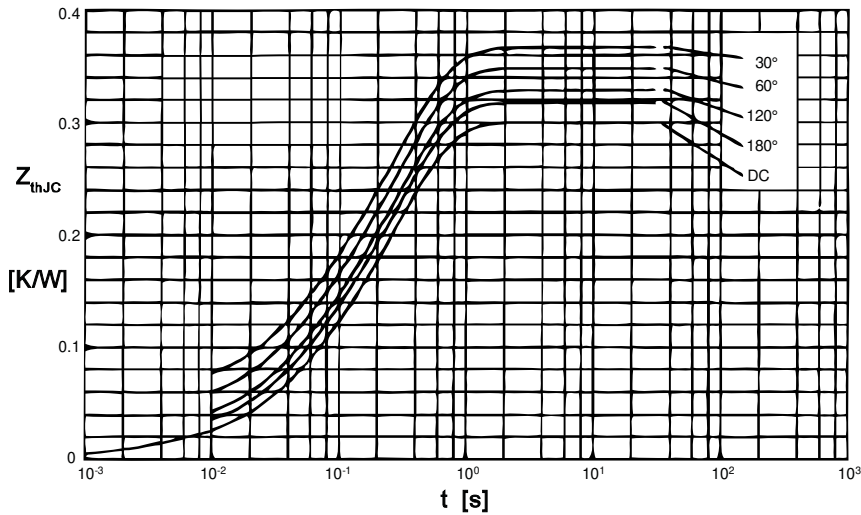


Fig. 9 Transient thermal impedance junction to case (per thyristor)

$R_{thJC}$  for various conduction angles  $d$ :

$d$	$R_{thJC}$ [K/W]
DC	0.30
180°	0.31
120°	0.33
60°	0.35
30°	0.37

Constants for  $Z_{thJC}$  calculation:

$i$	$R_{thi}$ [K/W]	$t_i$ [s]
1	0.008	0.0019
2	0.054	0.0470
3	0.238	0.3000

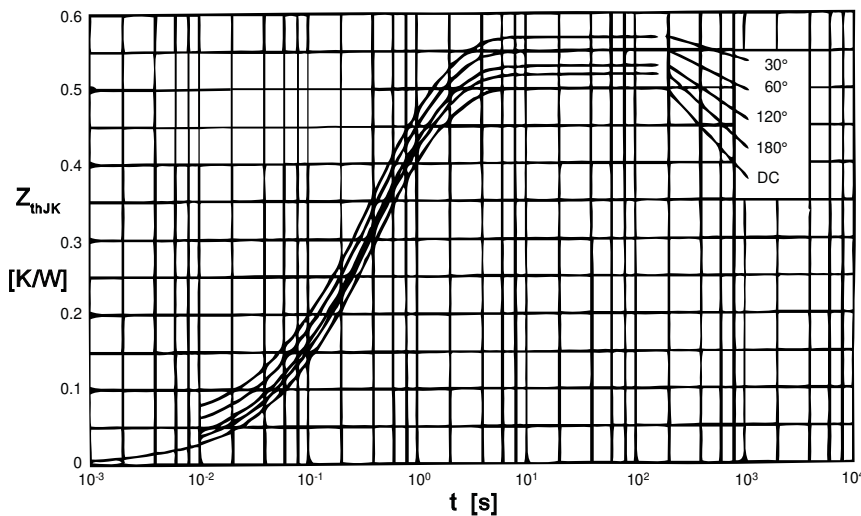


Fig. 10 Transient thermal impedance junction to heatsink (per thyristor)

$R_{thJK}$  for various conduction angles  $d$ :

$d$	$R_{thJK}$ [K/W]
DC	0.50
180°	0.51
120°	0.53
60°	0.55
30°	0.57

Constants for  $Z_{thJK}$  calculation:

$i$	$R_{thi}$ [K/W]	$t_i$ [s]
1	0.008	0.0019
2	0.054	0.0470
3	0.238	0.3000
4	0.200	1.2500